

L Number	Hits	Search Text	DB	Time stamp
1	227	257/687	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 20:49
2	1177	257/687	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 20:58
3	1684	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 21:08
4	1397	257/762	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 21:35
5	1854	257/763	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 21:52
6	812	257/766	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 21:53
-	317	257/738	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 20:49
-	2488	257/738 and (ball or bump or BGA or array)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 12:24
-	2208	257/738 and (ball or bump or BGA or array or flip)	USPAT	2004/07/08 12:24
-	2510	257/738 and (ball or bump or BGA or array or flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 12:25
-	2488	257/738 and (ball or bump or BGA or array)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 12:25
-	2188	257/738 and (ball or bump or BGA or array)	USPAT	2004/07/08 12:25
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 13:46
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 13:58
-	2670	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 13:51
-	716	257/738 not (257/738 and (ball or bump or BGA or array) and wir\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 13:51

-	5257	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 13:58
-	1673	257/666 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 14:27
-	323	257/667 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 14:27
-	3167	257/666	USPAT	2004/07/08 15:34
-	1671	257/666 not (257/666 and (ball or bump or BGA or array) and wir\$3)	USPAT	2004/07/08 14:29
-	0	conductive near epoxy with 257/777	USPAT	2004/07/08 14:31
-	34	electrically near conductive near epoxy and 257/777	USPAT	2004/07/08 14:35
-	39	electrically near conductive near epoxy and (438/108 or 438/109)	USPAT	2004/07/08 14:34
-	188	conductive near epoxy and 257/777	USPAT	2004/07/08 14:35
-	61	electrically with conductive near epoxy and 257/777	USPAT	2004/07/08 14:38
-	98	electrically with conductive near epoxy and (257/777 or 438/108 or 438/109)	USPAT	2004/07/08 14:40
-	134	electrically with conductive near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	USPAT	2004/07/08 14:50
-	141	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	USPAT	2004/07/08 14:56
-	0	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	JPO	2004/07/08 14:54
-	172	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760)	USPAT	2004/07/08 15:21
-	320	electrically with (conductive or "Ag" or silver) with epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760)	USPAT	2004/07/08 15:22
-	235	electrically with (conductive or "Ag" or silver) with epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760) and (ball or bump)	USPAT	2004/07/08 15:22
-	685	257/667	USPAT	2004/07/08 15:34
-	945	257/667	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:05
-	778	257/673	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:15
-	3181	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:10
-	2245	257/676	USPAT	2004/07/08 16:11
-	3329	257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:15
-	2717	257/773	USPAT	2004/07/08 16:39
-	2719	257/774	USPAT	2004/07/08 16:55
-	972	257/776	USPAT	2004/07/08 16:55

-	1162	257/776	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:10
-	2518	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:10
-	1783	257/784	USPAT	2004/07/08 17:19
-	861	257/684	USPAT	2004/07/08 17:20
-	1062	257/684	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:45
-	2342	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:49
-	3932	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:49
-	3410	257/778	USPAT	2004/07/08 18:11
-	2231	257/678	USPAT	2004/07/08 18:57
-	902	257/781	USPAT	2004/07/08 18:57
-	1001	257/781	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 18:58